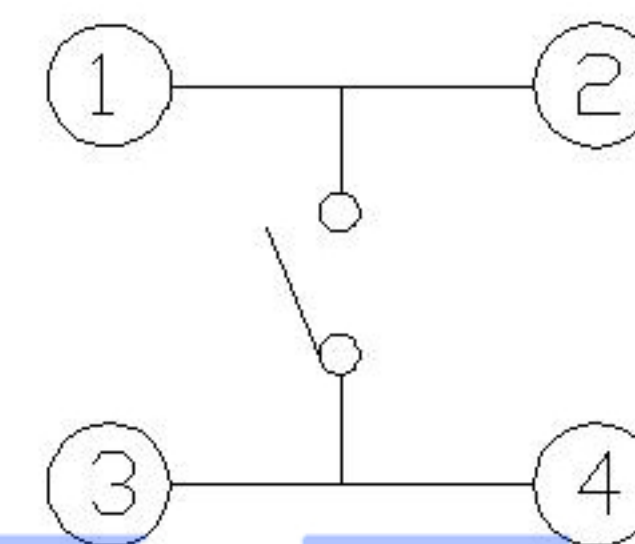
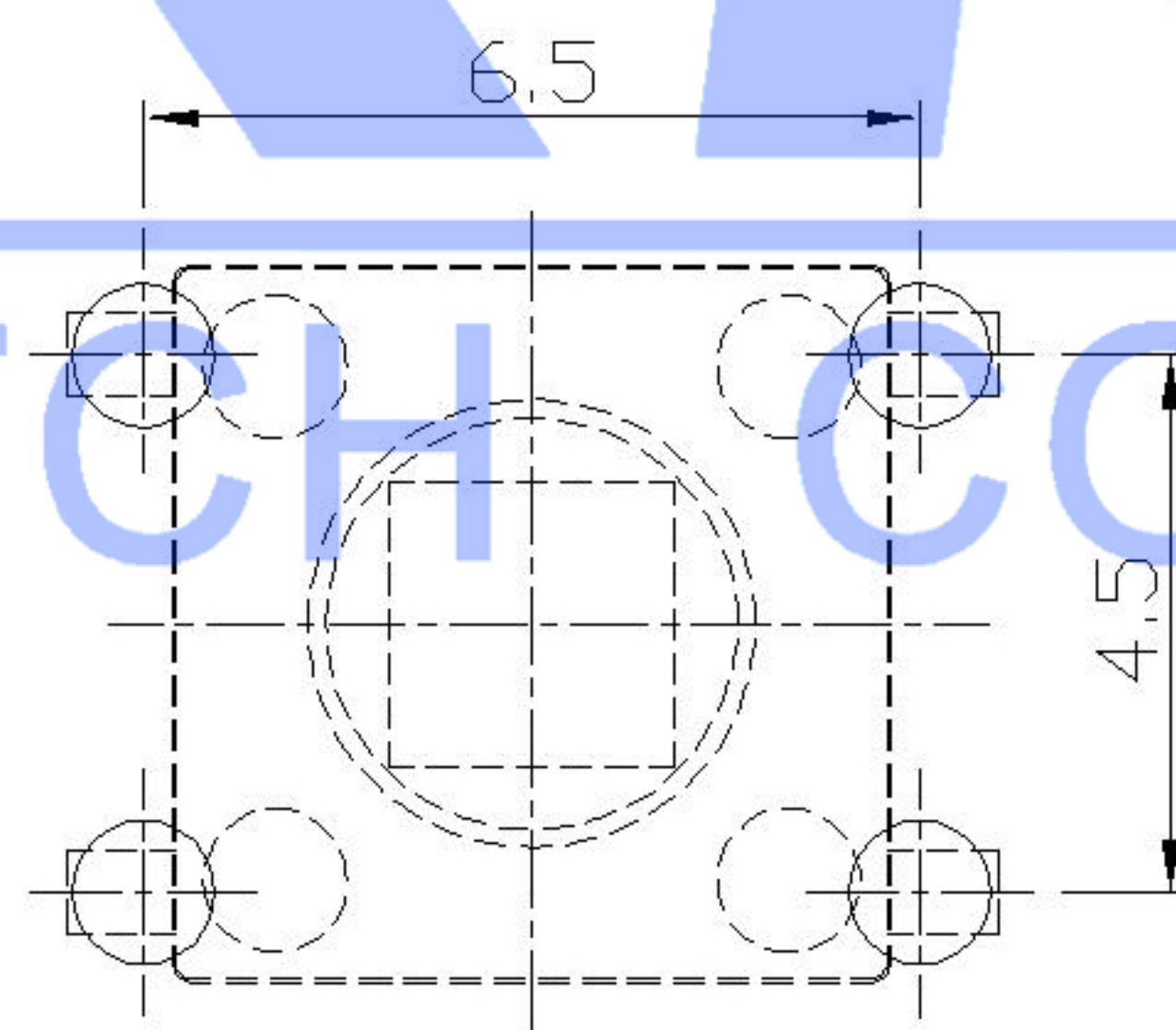
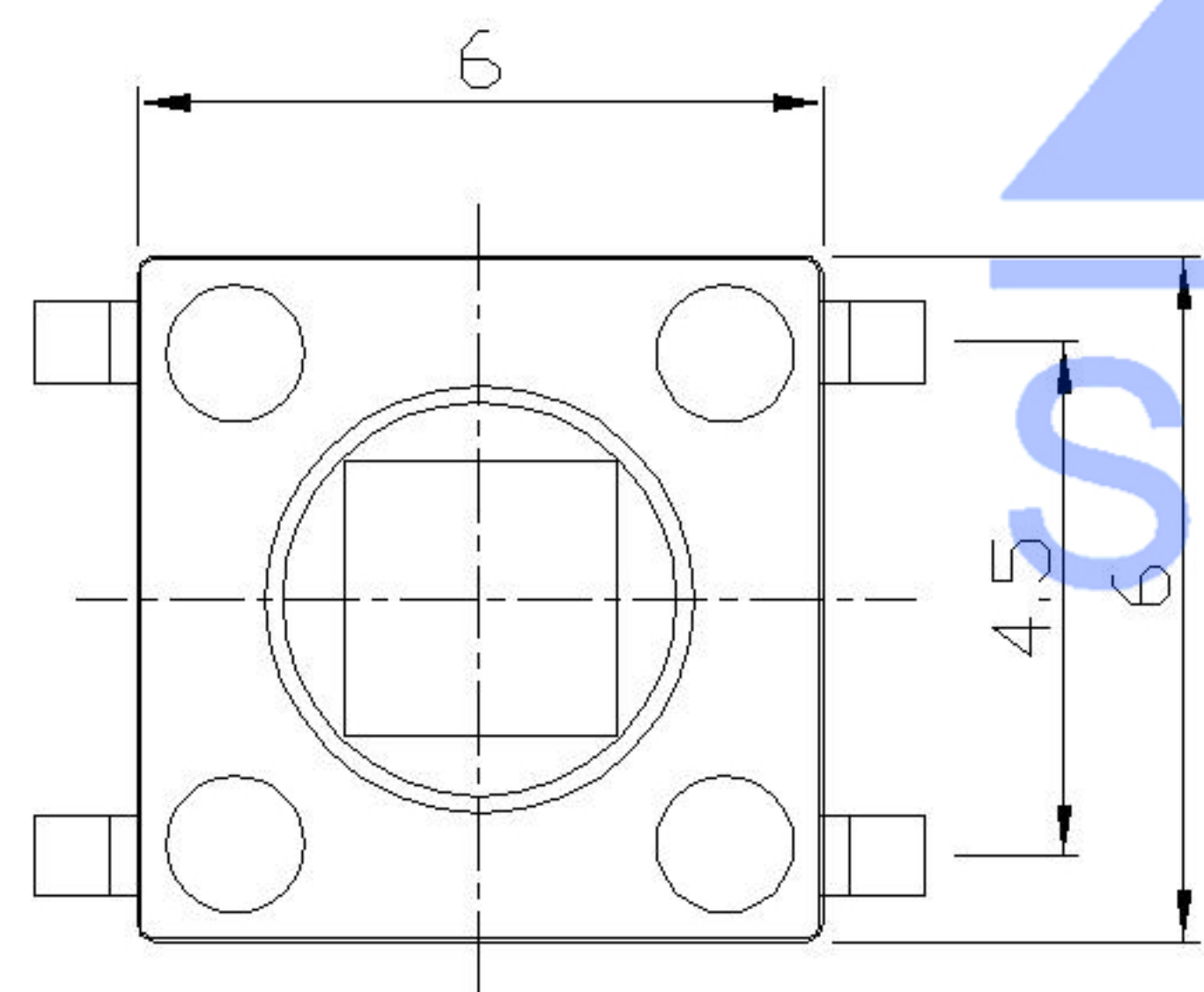


CIRCUIT DIAGRAM



P.C.B MOUNTING PATTERN DIMENSION  
The following soldering patterns are recommended for reflow soldering



**SPECIFICATION**

Con ac Ra ing 50mA 12V DC  
 Con ac Resis ance 100mΩ max.  
 Insula ion Resis ance 100MΩ min. 500V DC  
 Dielec ric S reng h 250V AC/1 minu e  
 Travel 0.25 mm  
 Opera ing Temp. -25 C +70 C  
 S orage Temp. -30 C +80 C

PAPT NO	TC-1102T-X
Operating force	A: 100gf B: 180gf C: 260gf
Height	H: 7.3

ΔX					ANGULAR	±5'	DSND		DATE		SCALE: N/A	MODEL TYPE:	TACT SWITCH	
ΔX					L f 4	±0.2	DWN		DATE		VIEW:	PART NO.:		
ΔX					4 < L f 16	±0.3	CHKD		DATE		UNIT: mm	DWG NO.:	TC-1102T-X	
MARK	DESCRIPTION	DATE	REVISED	APPROVED	16 < L f 63	±0.4	APPD		DATE		SIZE: A4	WEIGHT	SHEET	REVISION
					L > 63	±0.5	XKB INDUSTRIAL PRECISION CO., LIMITED					1.0g	1/1	A0
					UNSPECIFIED TOLERANCES									
REVISIONS														
www.xk-edg.cn www.helloxkb.com www.helloxkb.cn														